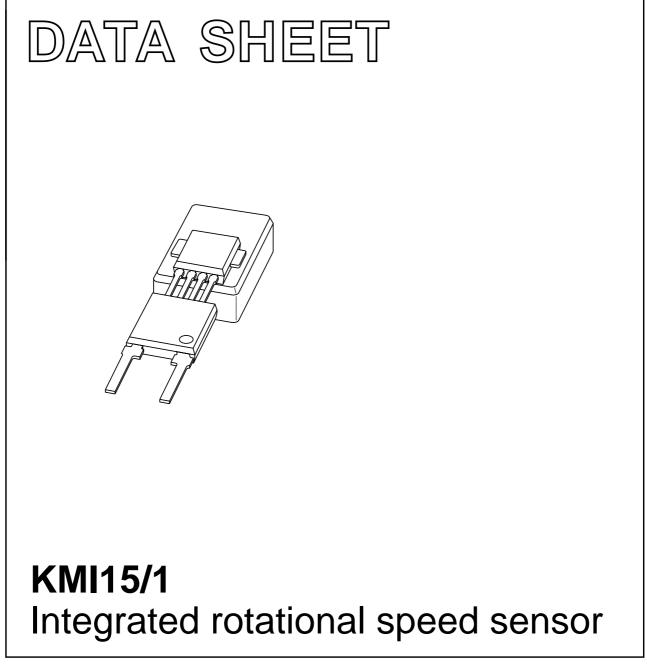
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1998 Mar 30 2000 Jun 26



FEATURES

- Digital current output signal
- Zero speed capability
- Wide air gap
- Wide temperature range
- Insensitive to vibration
- EMC resistant.

DESCRIPTION

The KMI15/1 sensor detects rotational speed of ferrous gear wheels and reference marks⁽¹⁾. The sensor consists of a magnetoresistive sensor element, a signal conditioning integrated circuit in bipolar technology and a magnetized ferrite magnet. The frequency of the digital current output signal is proportional to the rotational speed of a gear wheel.

CAUTION

Do not press two or more products together against their magnetic forces.

(1) The sensor contains a customized integrated circuit. Usage in hydraulic brake systems and in systems with active brake control is forbidden.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{CC}	DC supply voltage	-	12	-	V
I _{CC (low)}	current output signal low	-	7	-	mA
I _{CC (high)}	current output signal high	-	14	-	mA
d	sensing distance	0 to 2.5	0 to 2.9	_	mm
ft	operating tooth frequency	0	_	25000	Hz
T _{amb}	ambient operating temperature	-40	-	+85	°C

PINNING

PIN	DESCRIPTION
1	V _{CC}
2	V-

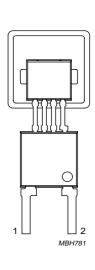


Fig.1 Simplified outline (SOT453B).

KMI15/1

LIMITING VALUES

In accordance with Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	DC supply voltage	T_{amb} = -40 to +85 °C; R_L = 115 Ω	-0.5	+16	V
T _{stg}	storage temperature		-40	+150	°C
T _{amb}	ambient operating temperature		-40	+85	°C
T _{sld}	soldering temperature	t ≤ 10 s	-	260	°C
	output short-circuit duration to GND		continuou	S	

CHARACTERISTICS

 $T_{amb} = 25 \text{ °C}$; $V_{CC} = 12 \text{ V}$; d = 2.1 mm; $f_t = 2 \text{ kHz}$; test circuit: see Fig.7; $R_L = 115 \Omega$; sensor positioning: see Fig.15; gear wheel: module 2 mm; material 1.0715; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CC (low)}	current output signal low	see Figs 6 and 8	5.6	7	8.4	mA
I _{CC (high)}	current output signal high	see Figs 6 and 8	11.2	14	16.8	mA
t _r	output signal rise time	C_L = 100 pF; see Fig.9; 10 to 90% value	_	0.5	-	μs
t _f	output signal fall time	C _L = 100 pF; see Fig.9; 10 to 90% value	-	0.7	-	μs
t _d	switching delay time	between stimulation pulse (generated by a coil) and output signal	_	1	_	μs
ft	operating tooth frequency	for both rotation directions	0	-	25000	Hz
d	sensing distance	see Fig.15 and note 1	0 to 2.5	0 to 2.9	_	mm
δ	duty cycle	see Fig.6	30	50	70	%

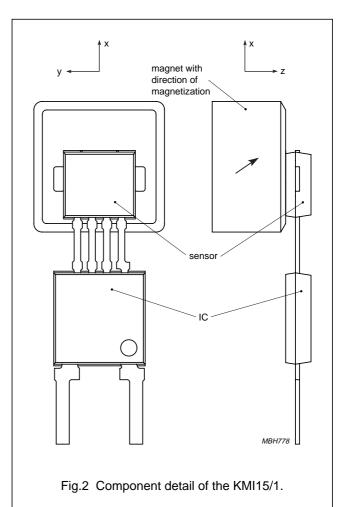
Note

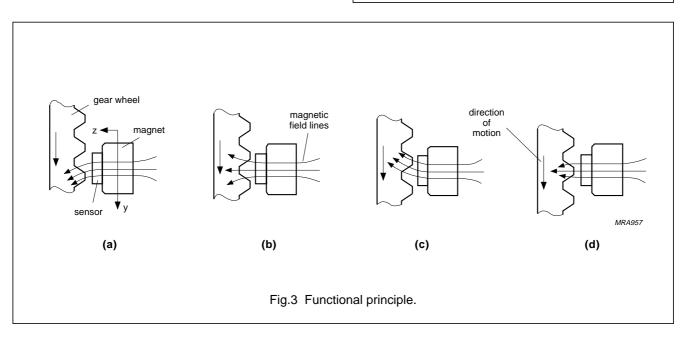
1. High rotational speeds of wheels reduce the sensing distance due to eddy current effects (see Fig.17).

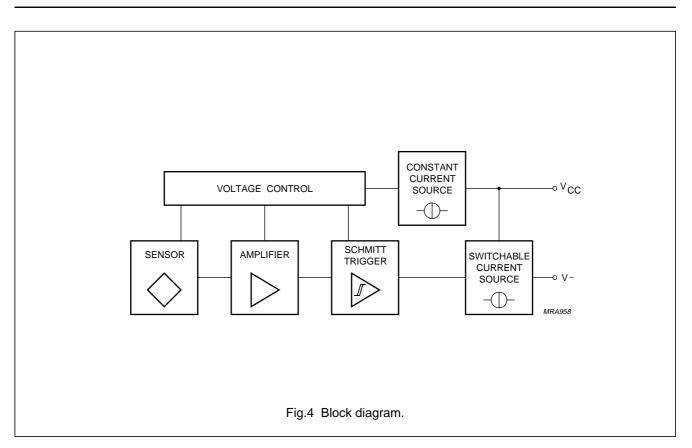
FUNCTIONAL DESCRIPTION

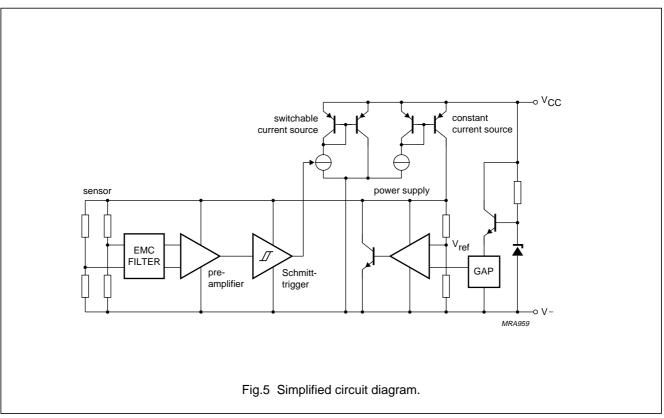
The KMI15/1 sensor is sensitive to the motion of ferrous gear wheels or reference marks. The functional principle is shown in Fig.3. Due to the effect of flux bending, the different directions of magnetic field lines in the magnetoresistive sensor element will cause an electrical signal. Because of the chosen sensor orientation and the direction of ferrite magnetization, the KMI15/1 is sensitive to movement in the 'y' direction in front of the sensor only (see Fig.2).

The magnetoresistive sensor element signal is amplified, temperature compensated and passed to a Schmitt trigger in the conditioning integrated circuit (Figs 4 and 5). The digital output signal level (see Fig.6) is independent of the sensing distance within the measuring range (Fig.14). A (2-wire) output current enables safe transfer of the sensor signal to the detecting circuit (see Fig.7). The integrated circuit housing is separated from the sensor element housing to optimize the sensor behavior at high temperatures.

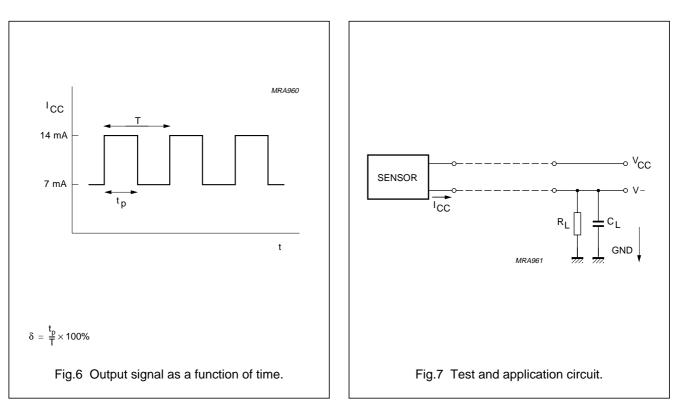




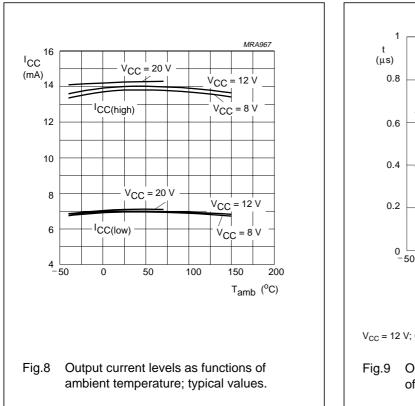




KMI15/1



APPLICATION INFORMATION



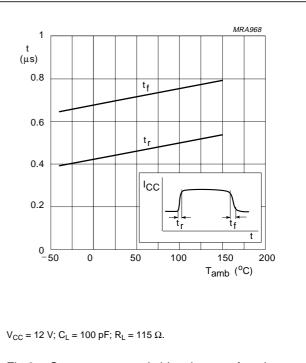


Fig.9 Output current switching times as functions of ambient temperature; typical values.

KMI15/1

MRA998

3

| y | (mm)

4

Mounting conditions

The recommended sensor position in front of a gear wheel is shown in Fig.15. The distance 'd' is measured between the sensor front and the tip of a gear wheel tooth. The KMI15/1 senses ferrous indicators like gear wheels in the \pm y direction only (no rotational symmetry of the sensor); see Fig.2. The effect of incorrect mounting positions on sensing distance is shown in Figs 11, 12 and 13. The symmetrical reference axis of the sensor corresponds to the axis of the ferrite magnet.

Environmental conditions

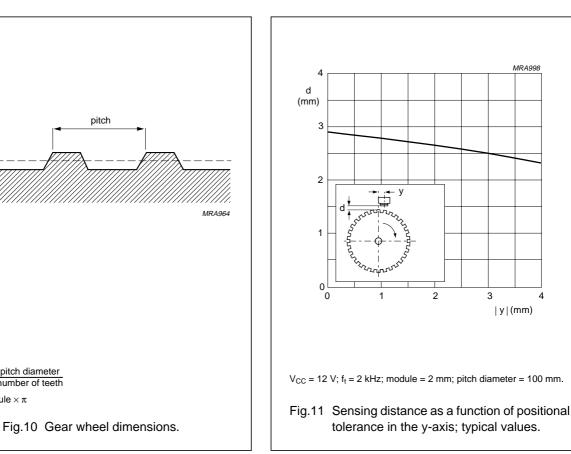
Due to eddy current effects the sensing distance depends on the tooth frequency (Fig.17). The influence of gear wheel module on the sensing distance is shown in Fig.16.

Gear Wheel Dimensions

SYMBOL	DESCRIPTION UNIT				
German DI	German DIN				
z	number of teeth				
d	diameter	mm			
m	module $m = d/z$	mm			
р	pitch p = $\pi \times m$ mm				
ASA; note1					
PD	pitch diameter (d in inch)	inch			
DP	diametric pitch DP = z/PD inch ⁻¹				
СР	circular pitch CP = π /DP inch				

Note

1. For conversion from ASA to DIN: m = 25.4 mm/DP; $p = 25.4 \text{ mm} \times \text{CP}.$



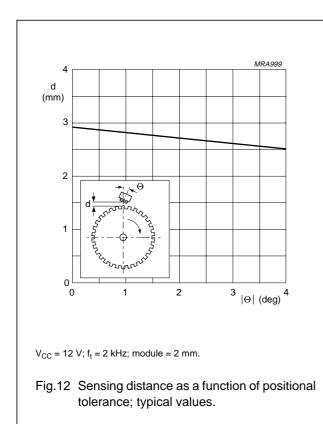
pitch

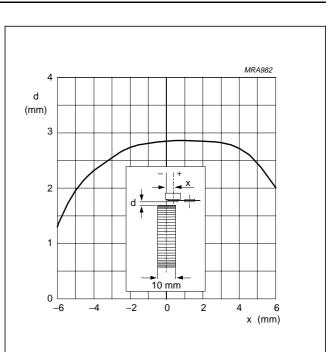
diameter

module = $\frac{\text{pitch diameter}}{\text{number of teeth}}$

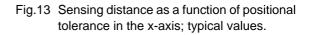
pitch = module $\times \pi$

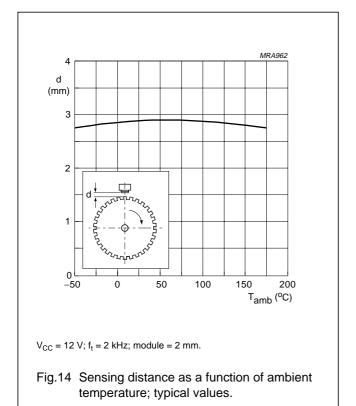
KMI15/1

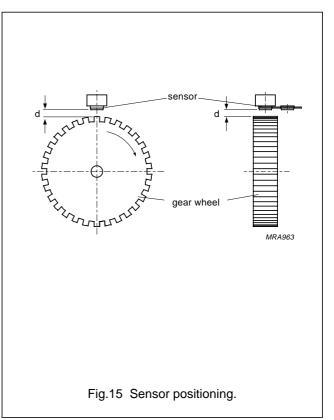


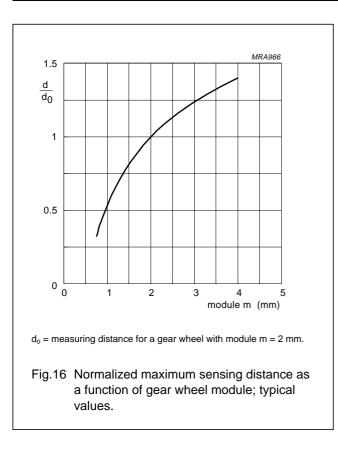


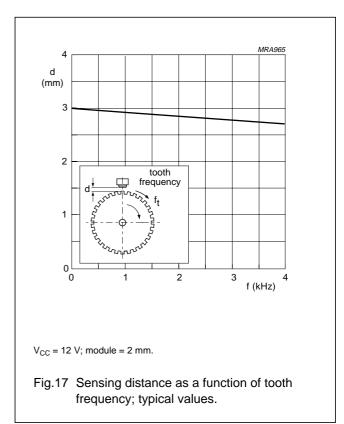
 V_{CC} = 12 V; f_t = 2 kHz; module = 2 mm.











KMI15/1

EMC

Figure 18 shows a recommended application circuit for automotive applications (wheel sensing $f_t < 5$ kHz). It provides a protection interface to meet Electromagnetic Compatibility (EMC) standards and safeguard against voltage spikes. Table 1 lists the tests which are applicable to this circuit and the achieved class of functional status. Protection against 'load dump' (test pulse 5 according to *"DIN 40839"*) means a very high demand on the protection circuit and requires a suitable suppressor diode with sufficient energy absorption capability. The board net often contains a central load dump protection that makes such a device in the protection circuit of the sensor module unnecessary.

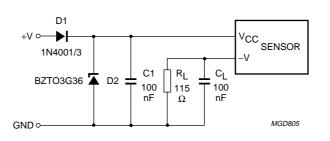
Tests for electrostatic discharge (ESD) were conducted in line with *"IEC 801-2"* to demonstrate the KMI15/1's handling capabilities. The *"IEC 801-2"* test conditions were: C = 150 pF, R = 150 Ω , V = 2 kV.

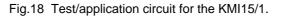
Electromagnetic disturbances with fields up to 150 V/m and f = 1 GHz (ref. "*DIN 40839*") have no influence on performance.

Table 1	EMC test results	

_...

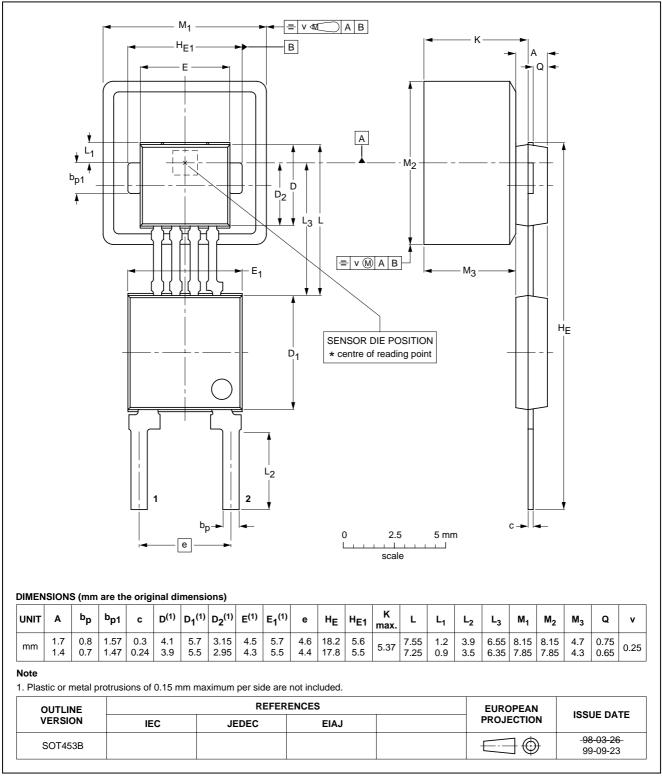
EMC REF. DIN 40839	SYMBOL	MIN. (V)	MAX. (V)	REMARKS	CLASS
Test pulse 1	V _{LD}	-100	_	t _d = 2 ms	С
Test pulse 2	V _{LD}	_	100	$t_{d} = 0.2 \text{ ms}$	A
Test pulse 3a	V _{LD}	-150	_	t _d = 0.1 μs	A
Test pulse 3b	V _{LD}	_	100	t _d = 0.1 μs	A
Test pulse 4	V _{LD}	-7	_	t _d = 130 ms	В
Test pulse 5	V _{LD}	_	120	t _d = 400 ms	В





PACKAGE OUTLINE

Plastic single-ended combined package; magnetoresistive sensor element; bipolar IC; magnetized ferrite magnet (8 x 8 x 4.5 mm); 2 in-line leads



KMI15/1

SOT453B

KMI15/1

DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS (1)
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

DISCLAIMERS

Life support applications — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

KMI15/1

NOTES

KMI15/1

NOTES

KMI15/1

NOTES

Philips Semiconductors – a worldwide company

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB, Argentina: see South America Tel. +31 40 27 82785, Fax. +31 40 27 88399 Australia: 3 Figtree Drive, HOMEBUSH, NSW 2140, New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. +61 2 9704 8141, Fax. +61 2 9704 8139 Tel. +64 9 849 4160, Fax. +64 9 849 7811 Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213, Tel. +43 1 60 101 1248. Fax. +43 1 60 101 1210 Norway: Box 1, Manglerud 0612, OSLO, Tel. +47 22 74 8000, Fax. +47 22 74 8341 Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6, 220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773 Pakistan: see Singapore Belgium: see The Netherlands Philippines: Philips Semiconductors Philippines Inc., 106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI, Brazil: see South America Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474 Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor, Poland: Al.Jerozolimskie 195 B, 02-222 WARSAW, 51 James Bourchier Blvd., 1407 SOFIA, Tel. +359 2 68 9211, Fax. +359 2 68 9102 Tel. +48 22 5710 000, Fax. +48 22 5710 001 Portugal: see Spain Canada: PHILIPS SEMICONDUCTORS/COMPONENTS, Tel. +1 800 234 7381, Fax. +1 800 943 0087 Romania: see Italy China/Hong Kong: 501 Hong Kong Industrial Technology Centre, Russia: Philips Russia, UI. Usatcheva 35A, 119048 MOSCOW, 72 Tat Chee Avenue, Kowloon Tong, HONG KONG, Tel. +7 095 755 6918, Fax. +7 095 755 6919 Tel. +852 2319 7888, Fax. +852 2319 7700 Colombia: see South America Czech Republic: see Austria Denmark: Sydhavnsgade 23, 1780 COPENHAGEN V, Tel. +45 33 29 3333, Fax. +45 33 29 3905 Finland: Sinikalliontie 3, FIN-02630 ESPOO, Tel. +358 9 615 800, Fax. +358 9 6158 0920 France: 51 Rue Carnot, BP317, 92156 SURESNES Cedex, Tel. +33 1 4099 6161, Fax. +33 1 4099 6427 Germany: Hammerbrookstraße 69, D-20097 HAMBURG, Tel. +49 40 2353 60, Fax. +49 40 2353 6300 Hungary: see Austria India: Philips INDIA Ltd, Band Box Building, 2nd floor, 254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025, Tel. +91 22 493 8541, Fax. +91 22 493 0966 Indonesia: PT Philips Development Corporation, Semiconductors Division, Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510, Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080 Ireland: Newstead, Clonskeagh, DUBLIN 14, Tel. +353 1 7640 000, Fax. +353 1 7640 200 Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053, TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007 Italy: PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI), Tel. +39 039 203 6838. Fax +39 039 203 6800 Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057 Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL, Tel. +82 2 709 1412, Fax. +82 2 709 1415 Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR, Tel. +60 3 750 5214, Fax. +60 3 757 4880 Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905, Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087 Middle East: see Italy

For all other countries apply to: Philips Semiconductors,

Marketing Communications, Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

© Philips Electronics N.V. 2000

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

613520/03/pp16

Date of release: 2000 Jun 26

Document order number: 9397 750 07251

SCA70

Let's make things better.







Vietnam: see Singapore Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD, Tel. +381 11 3341 299, Fax.+381 11 3342 553

Internet: http://www.semiconductors.philips.com